



Material Content Data Sheet



Sales Product Name	IPI80N04S2-04			Issued		29. August 2013		
MA#	MA000275863							
Package	PG-TO262-3-1			Weight*		1576.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.78	0.78	7798	7798
leadframe	non noble metal	iron	7439-89-6	0.957	0.06		607	
	inorganic material	phosphorus	7723-14-0	0.287	0.02		182	
	non noble metal	copper	7440-50-8	955.892	60.65	60.73	606333	607122
wire	non noble metal	aluminium	7429-90-5	5.382	0.34	0.34	3414	3414
encapsulation	organic material	carbon black	1333-86-4	8.706	0.55		5523	
	plastics	epoxy resin	-	95.770	6.07		60748	
	inorganic material	silicondioxide	60676-86-0	475.950	30.19	36.81	301901	368172
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9640	9640
plating	non noble metal	nickel	7440-02-0	0.228	0.01		145	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	145
solder	noble metal	silver	7440-22-4	0.146	0.01		93	
	non noble metal	tin	7440-31-5	0.117	0.01		74	
	non noble metal	lead	7439-92-1	5.584	0.35	0.37	3542	3709
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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